

SPECIFICATION AMENDMENTS

Amend the title appearing on page 1 starting in line 1 as follows:

METHOD FOR MANUFACTURING AN ELECTRONIC COMPONENT AND A
METHOD OF MANUFACTURING THE SAME

Amend the abstract of the disclosure appearing on page 19 starting in line 3 as follows:

A method of manufacturing an An electronic component is obtained by forming a primer plating layer of a material which is poorly wettable to a weld brazing material 3 on a base member 11X of with a contact 11 having a terminal section 111 for brazing and a contact section 112, includes steps that construct a contact base member of a material that is poorly wettable, forms a primer plating layer of a material that is poorly wettable to the weld brazing material on the base member, and then forming forms a finish plating layer of a material which that is highly wettable to the weld brazing material on the primer plating layer, and . An exposed region of the poorly wettable primer plating layer is formed thereafter by selectively removing removes a portion of the finish plating layer at the terminal section 111 and served to obtain an exposed region of the primer plating layer that serves as an arresting region for arresting the weld brazing material 3 from creeping up and migrating along the highly wettable finish plating layer in brazing the terminal section 111 to the brazing pad 22 of a wiring board 2.